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- 3-State Version of the 'ALS151
- 3-State Outputs Interface Directly With System Bus
- Perform Parallel-to-Serial Conversion
- Complementary Outputs Provide True and Inverted Data
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

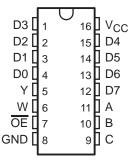
description

These data selectors/multiplexers contain full binary decoding to select one-of-eight data sources and feature controlled complementary 3-state outputs.

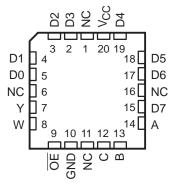
The 3-state outputs can interface with and drive data lines of bus-organized systems. With all but one of the common outputs disabled (at the high-impedance state), the low impedance of the signal-enabled output drives the bus line to a high or low logic level. Both outputs are controlled by the output-enable (\overline{OE}) input. The outputs are disabled when \overline{OE} is high.

The SN54ALS251 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS251 is characterized for operation from 0°C to 70°C.

SN54ALS251 . . . J PACKAGE SN74ALS251 . . . D OR N PACKAGE (TOP VIEW)



SN54ALS251 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

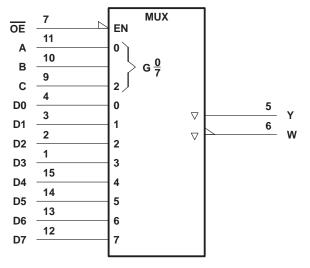
FUNCTION TABLE

	INP	OUT	DUTC					
	SELECT	•	ŌĒ	OUTPUTS				
С	В	Α	O _E	Υ	W			
X	Χ	Χ	Н	Z	Z			
L	L	L	L	D0	D0			
L	L	Н	L	D1	D1			
L	Н	L	L	D2	D2			
L	Н	Н	L	D3	D3			
Н	L	L	L	D4	D4			
Н	L	Н	L	D5	D5			
Н	Н	L	L	D6	D6			
Н	Н	Н	L	D7	D7			

D0, D1, . . . D7 = the level of the respective D input

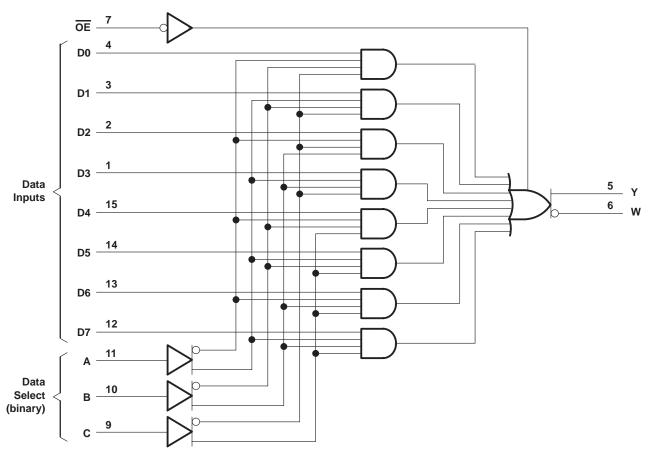
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logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.



SN54ALS251, SN74ALS251 1-OF-8 DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	
Input voltage, V _I	
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN54ALS251	–55°C to 125°C
SN74ALS251	0°C to 70°C
Storage temperature range	-65°C to 150°C

recommended operating conditions

		SN54ALS251		51	SN	LINUT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
IOH	High-level output current			-1			-2.6	mA
l _{OL}	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		7507.0	TEST COMPITIONS		54ALS2	51	SN				
		TEST CONDITIONS			TYP‡	MAX	MIN	TYP‡	MAX	UNIT	
VIK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		VCC -2	<u>)</u>			
V_{OH}		V 45V	$I_{OH} = -1 \text{ mA}$	2.4	3.3					V	
		V _{CC} = 4.5 V	$I_{OH} = -2.6 \text{ mA}$				2.4	3.2			
\/-·		V 45V	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	0.4 V	
VOL		V _{CC} = 4.5 V	$I_{OL} = 24 \text{ mA}$					0.35	0.5	V	
lozh		V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μΑ	
lozL		V _{CC} = 5.5 V,	V _O = 0.4 V			-20			-20	μΑ	
II		V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA	
lιΗ		V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ	
I _{IL}		$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-0.1			-0.1	mA	
ΙΟ§		$V_{CC} = 5.5 V,$	V _O = 4.5 V	-20		-112	-30		-112	mA	
la a	Enabled	V	Inputs at GND		7	10		7	10	m ^	
ICC	Disabled	$V_{CC} = 5.5 \text{ V}$	Inputs at 4.5 V		9.4	14		9.4	14	mA	

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, los.

SN54ALS251, SN74ALS251 1-OF-8 DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS SDAS215A - APRIL 1982 - REVISED DECEMBER 1994

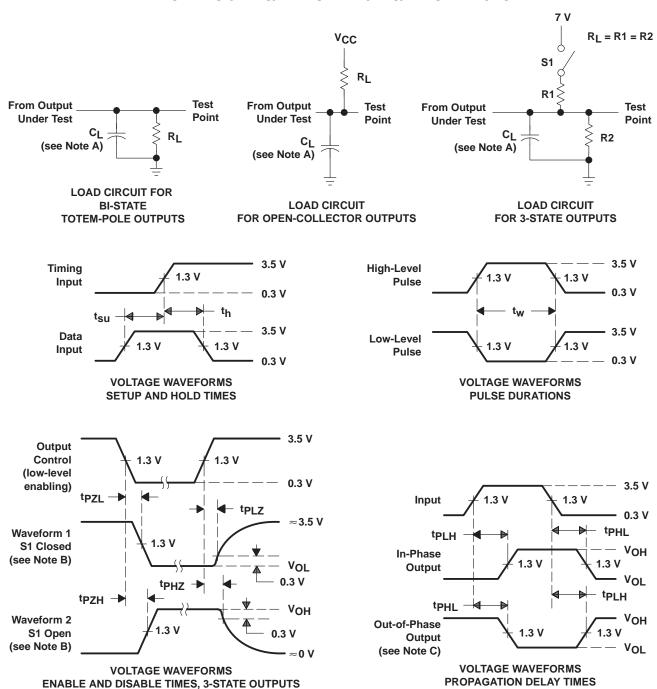
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C C _L R1 R2 T _A	UNIT			
			SN54A	LS251	SN74A		
			MIN	MAX	MIN	MAX	
t _{PLH}	A D as C	V	1	21	5	18	
t _{PHL}	A, B, or C	Y	7	34	8	24	ns
tpLH	A D as C	10/	5	38	8	24	ns
^t PHL	A, B, or C	W	7	26	7	23	
t _{PLH}	Any D	Y	2	15	2	10	ns
^t PHL	Any D	Y	3	23	3	15	
t _{PLH}	A D	144	3	25	3	15	ns
^t PHL	Any D	W	3	20	3	15	
^t PZH	OE	V	3	21	3	15	
tPZL	OE .	Y	3	19	3	15	ns
^t PZH	OE	144	3	21	3	15	
t _{PZL}] UE	W	3	19	3	15	ns
^t PZH	ŌĒ	V	2	12	2	10	
tPZL	UE	Y	1	18	1	10	ns
^t PZH	OE	W	2	12	2	10	ns
t _{PZL}		VV	1	18	1	10	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- All input pulses have the following characteristics: PRR \leq 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
- The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
84135012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84135012A SNJ54ALS 251FK	Samples
8413501EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8413501EA SNJ54ALS251J	Samples
8413501FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8413501FA SNJ54ALS251W	Samples
SN54ALS251J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54ALS251J	Samples
SN74ALS251D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS251	Samples
SN74ALS251DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS251	Samples
SN74ALS251N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS251N	Samples
SNJ54ALS251FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84135012A SNJ54ALS 251FK	Samples
SNJ54ALS251J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8413501EA SNJ54ALS251J	Samples
SNJ54ALS251W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8413501FA SNJ54ALS251W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

PACKAGE OPTION ADDENDUM

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(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS251, SN74ALS251:

Catalog: SN74ALS251

Military: SN54ALS251

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS251DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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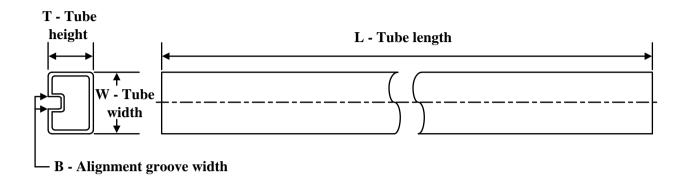
*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN74ALS251DR	SOIC	D	16	2500	340.5	336.1	32.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
84135012A	FK	LCCC	20	1	506.98	12.06	2030	NA
8413501FA	W	CFP	16	1	506.98	26.16	6220	NA
SN74ALS251D	D	SOIC	16	40	507	8	3940	4.32
SN74ALS251N	N	PDIP	16	25	506	13.97	11230	4.32
SN74ALS251N	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54ALS251FK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54ALS251W	W	CFP	16	1	506.98	26.16	6220	NA

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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